

Prominent Conference Speakers in 2026

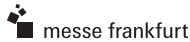
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 BOSCH	 CPI	 Charge Evolution	 ZEMIS UNIVERSITY OF MANAGEMENT & TECHNOLOGY	 SEMI-FUTURE	 CEPREI
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* No specific order

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Paper Submission

pcim
ASIA SHANGHAI

24 – 26 August 2027
Shanghai New International
Expo Centre, China

PCIM Asia Shanghai – International Exhibition and
Conference for Power Electronics, Intelligent Motion,
Renewable Energy and Energy Management

Call for Paper
2027

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PCIM Asia Shanghai Conference 2027 Advisory Board

General Conference Director



Leo Lorenz
ECPE, DE

» Being able to identify the industry's development trends, this makes the conference even more important for industry players to focus on developing the right products and technologies to meet the demands of the future. «

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Become a Speaker

As the leading international exhibition and conference for power electronics, the PCIM Asia Shanghai Conference is the international meeting point for industry and academia. This combination is what makes this event unique.

Join us and inspire others with your ideas!

Maximum visibility in the power electronics community

As a speaker at the PCIM Asia Shanghai Conference, you will draw the attention of more than 500 participants to your research topic. Do take the opportunity to present your publication in Shanghai and enter into direct exchange on your topic with representatives both from industry and academia!

- **Publishing** of your paper in the PCIM Asia Shanghai Conference proceedings as well as databases like EI Compendex, IEEE Xplore, IET Inspec-Direct and Scopus.
- **Visibility** by presenting your scientific work to more than 500 participants.
- **Direct feedback** on your topic from experts of industry and academia.
- **Networking** and making new valuable contacts in the power electronics community.
- **Market overview** at the highly relevant exhibition with all representatives from the industry.

Conference Award Sponsors



Deadlines to note

- ▶ Submission of abstract until **4 March 2027**
- ▶ Notification of acceptance in **May 2027**
- ▶ Submission of full paper before **20 June 2027**

★ The presentation language is ENGLISH

Payment

Academia
RMB 750 per paper

Industry
RMB 1,500 per paper

* Submit with no limit. Presenting author get free conference entry.

Your chance to win an award

The awards will be selected by the Advisory Board from the accepted papers, and will be granted at the conference award ceremony.



1 winner
Prize with RMB 8,000



1 winner
Prize with RMB 8,000



5 winners
Prize with RMB 2,000/each



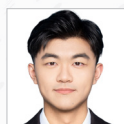
1 winner/session
Prize with RMB 1,000/each

Award Winners 2026

BEST PAPER AWARD WINNER



This award is sponsored by:



Low-Voltage p-GaN Gate HEMTs on 200-mm GaN-on-Si Platform with Record-Low $R_{ON, SP}$ and $R_{ON} \times Q_G$ for Advanced AI Power Delivery

Yuhao Wang, Yu Shi, Yan Cheng, David Zhou, Xinying Huang, Yu Zhang, Changan Li, Zidong Cai, Haolin Hu, Wei Zeng, Xiaoping Wang, Yuxi Wan, Shenzhen Pinghu Laboratory, China
Yan Cheng, Zongjie Zhou, Yat Hon Ng, Kevin J. Chen, The Hong Kong University of Science and Technology, China

YOUNG ENGINEER AWARD WINNER



This award is sponsored by:



Lightweight Arc Fault Detection by Optimized Machine Learning with Multi-dimensional Features

Yanzeng Wen, ASTRI Science and Technology Research (Shenzhen) Company Limited, CN
Victor Cheung, Hong Kong Applied Science and Technology Research Institute, CN

UNIVERSITY SCIENTIST AWARD



This award is sponsored by:



- ◆ **Non-Destructive Bond Wire Failure Detection in SiC Power Transistors Using Reflectometry Signals**
Valentina Afanasenko, Marius Niculescu, Ingmar Kallfass, University of Stuttgart, Germany
Markus Pfeiffer, Tim Sailer, Robert Bosch GmbH, Germany
- ◆ **A Solid-State High-voltage High-frequency Pulse Power Supply with Adjustable Pulse Speed for Multi Load Types**
Xin Li, Yifei Luo, Fei Xiao, Weichao Li, Honglin Li, National Key Laboratory of Electromagnetic Energy, Naval University of Engineering, China
Rui Zhang, School of Integrated Circuits, Wuhan University, China
Fengming Yang, School of Electrical and Electronic Engineering, Huazhong University of Science and Technology, China
- ◆ **A Three-Module Parallel Megahertz Inverter System with Wide Power Regulation Range**
Xinyi Yan, Yueshi Guan, Yijie Wang, Dianguo Xu, Harbin Institute of Technology, China
- ◆ **A Dual-Symmetric S-Channel Composite Heatsink for High-Reliability PEBB Modules**
Jiahao Zheng, Haoqi Zhu, Hongyu Feng, Xiaoshuang Li, Guozhu Chen, Zhejiang University, China
Haoqi Zhu, Hong Qin, Shaoxing Institute, Zhejiang University, China
- ◆ **A Robust PPO-based Control Scheme for 1 MHz DC-DC Converters with Multi-Domain Disturbance**
Chuanchuan Liang, Chaohong Zhang, You Du, Yida Chen, Guanghui Liu, Xueyong Zhang, Shen Xu, Weifeng Sun, Southeast University, China
Yunwu Zhang, National Silicon Integrated Circuit Technology (Wuxi) Co., Ltd., China

EXCELLENT POSTER AWARD



This award is sponsored by:



This award will be conducted on-site by the Session Chair based on paper quality, poster design, presentation, and Q&A performance.

Conference topics

1. Advanced Power Semiconductors

- 1.1 High Power Semiconductors
- 1.2 MOSFETs, IGBTs, FREDs & Schottkys
- 1.3 Power Modules and Power Hybrids
- 1.4 SiC Devices
- 1.5 GaN Devices
- 1.6 Other Wide Bandgap Devices
- 1.7 Power Supply Control IC and Power Management ICs
- 1.8 Gate Driver and Device Protection
- 1.9 IPM and Power Electronic Building Blocks

2. Packaging and Reliability

- 2.1 Packaging and Interface Technologies
- 2.2 Advanced Cooling Systems
- 2.3 Thermal Management and Simulations
- 2.4 Power Electronic Components Reliability and Life Time Prediction
- 2.5 Power Embedding
- 2.6 High Power Density Designs
- 2.7 Design Automation and Methodology

3. Passive Components and Integration

- 3.1 Higher Frequency and Low Loss Materials & Techniques for Inductors and Capacitors
- 3.2 Planar Inductors and Transformers and Thin Film Magnetic Component
- 3.3 Filters and Passive Integration

4. AC/DC Converter

- 4.1 High Efficiency/High Density Power Converters/Inverters
- 4.2 Resonant and Quasi Resonant Topologies for Power Supplies
- 4.3 Stand-alone Power Supplies (Adapters) and on Board Supplies
- 4.4 New Topologies (Single Switch, Phase Shift, ZVS, ZCS, ZVZCS)

5. DC/DC Converter

- 5.1 DC/DC Converter Topologies for Enhanced Efficiency and Control
- 5.2 Synchronous Rectification
- 5.3 Smart Battery Management Concepts
- 5.4 Point of Load Converters
- 5.5 New Topologies for Distributed Power Supply Systems (Single or Multi- Stage Architecture, ZVS, ZCS, ZVZCS)

6. Digital Power Conversion

- 6.1 PMBus and other Digital Power Control Protocols
- 6.2 Digital Control for Power Converters
- 6.3 Advantages of Digital Power Conversion and Associated Challenges
- 6.4 System on a Chip (SOC)
- 6.5 Energy Harvesting

7. Motor Drive & Motion Control

- 7.1 Home Appliances
- 7.2 Small Power Motor “General Purpose Drive” with Highly Sophisticated Control Strategies and Low Cost Solutions
- 7.3 New Converter/Inverter Types for Single- and Three Phase Systems
- 7.4 Advanced Motor Concepts for Industrial Application and Traction Drives
- 7.5 New Control Architectures DSP, Microcontroller or FPGA
- 7.6 Advanced Sensor Concepts for Motor Drives
- 7.7 Intelligent Motion Control and Architecture

8. High Frequency Power Electronic Converters and Inverters

- 8.1 Thermal Design, Packaging and EMI Issues
- 8.2 Sensors Specific to Power Electronics (e.g. Voltage, Current, Power, Frequency, Phase, Temperature)
- 8.3 Techniques to Reduce Switching Losses to Improve Efficiency and Reduce Size and Weight
- 8.4 Wireless Power Transfer

9. Automotive Power Electronics and Electrified Transportation

- 9.1 Hybrid / Electric Vehicle
- 9.2 MOSFET, IGBT and SiC Modules in Motor Traction and Propulsion Applications
- 9.3 DC/DC Conversion in Transportation Systems
- 9.4 Bidirectional DC/DC Converters
- 9.5 Electronics for Powertrain and Power Management
- 9.6 Energy Storage and Management, including Battery Types, Super Capacitors and Fly Wheels
- 9.7 DC Circuit Breaker
- 9.8 Charging Station Technology

Conference topics

10. System Reliability

- 10.1 Reliability and Health Management of Power Electronic Components and Systems
- 10.2 Fail-safe and Fault-tolerant Applications
- 10.3 Redundancy Concepts in Power Electronics
- 10.4 Life Cycle Design and Cost Analysis

11. Power Quality Solutions

- 11.1 UPS Systems and Inverters
- 11.2 Active Power Filter (APF), DVR, SVG
- 11.3 Energy Storage System
(Battery Technologies, Flywheel, Super (ultra) Capacitors)
- 11.4 Harmonics and Power Factor Correction
- 11.5 Electromagnetic Compatibility and Immunity

12. Smart Grid Power Electronics

- 12.1 Grid Inverter Control
- 12.2 Battery Charging and V2G
- 12.3 Energy Storage System and Control
- 12.4 Micro-Grid
- 12.5 Solid State Transformers
- 12.6 Medium Voltage Multilevel Converters
- 12.7 Modular Multilevel Converters
- 12.8 Novel Converter Topologies
- 12.9 Wind Energy Systems
- 12.10 Solar and Photovoltaic Energy Systems
- 12.11 Communication, Cyber Security and Artificial Intelligence

13. Power Electronics in Transmission Systems

- 13.1 FACTS
- 13.2 Converters for Offshore/Onshore HVDC Links
- 13.3 Power Generation, Transmission and Distribution
- 13.4 DC Grids
- 13.5 HVDC Systems
- 13.6 Digital Twin for Transmission Equipment

14. AI in Power and Energy Systems

- 14.1 Smart Grid Management using AI
- 14.2 AI in power Load Balancing
- 14.3 Intelligent Fault Detection and Diagnostics
- 14.4 Predictive Maintenance of Electrical Infrastructure

15. AI in Renewable Energy Systems

- 15.1 Intelligent control of battery energy storage systems

16. AI in Electrical Machines and Drives

- 16.1 Machine Learning for fault diagnosis in induction motors
- 16.2 Predictive maintenance of electrical machines

17. AI in Power Electronics

- 17.1 AI based control of DC-DC And AC-AC Converters
- 17.2 Intelligent inverter design for grid-tied applications
- 17.3 Fault detection in power electronic circuits using AI
- 17.4 Predictive thermal management in power modules
- 17.5 AI-optimized switching strategies to reduce harmonics

18. AI in power Quality Monitoring

- 18.1 AI for classification of power failure probability

19. AI in Electric Vehicle (EV) Power Systems

- 19.1 Smart charging infrastructure using AI
- 19.2 Battery State of Health (SoH) and State of Charge (SoC) prediction
- 19.3 AI-based powertrain optimization
- 19.4 Load management of EV charging in smart grids